



### DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub> max T <sub>A</sub> = 25°C
30V	16mΩ @ V <sub>GS</sub> = 10V	9.8A
	$22m\Omega @ V_{GS} = 4.5V$	8.4A

## **Description and Applications**

This MOSFET has been designed to minimize the on-state resistance  $(R_{DS(on)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

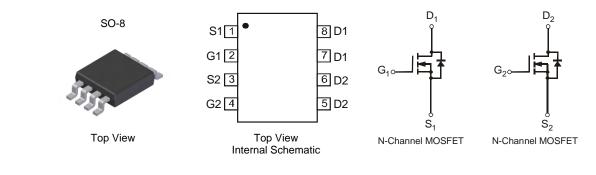
- Backlighting
- Power Management Functions
- DC-DC Converters

### **Features and Benefits**

- 100% avalanche rated part
- Low R<sub>DS(on)</sub> minimizes conduction losses
- Low Q<sub>g</sub> minimizes switching losses
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device, Halogen and Antimony Free (Note 2)
- Qualified to AEC-Q101 standards for High Reliability

## **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.076 grams (approximate)



### Ordering Information (Note 3)

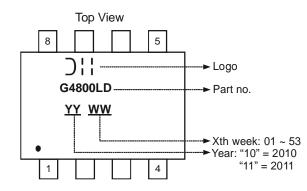
Part Number	Qualification	Case	Packaging
DMG4800LSD-13	Commercial	SO-8	2500 / Tape & Reel
DMG4800LSDQ-13	Automotive	SO-8	2500 / Tape & Reel

Notes: 1. No purposefully added lead.

2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.

3. For packaging details, go to our website at http://www.diodes.com.

### **Marking Information**





# Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V <sub>DSS</sub>	30	V
Gate-Source Voltage			V <sub>GSS</sub>	±25	V
Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V	Steady State	$T_A = 25^{\circ}C$ $T_A = 70^{\circ}C$	lo	7.5 6.0	А
	t<10s	$T_A = 25^{\circ}C$ $T_A = 70^{\circ}C$	ID	9.8 7.7	А
Continuous Drain Current (Note 5) V <sub>GS</sub> = 4.5V	Steady State	$T_A = 25^{\circ}C$ $T_A = 70^{\circ}C$	ID	6.4 5.0	A
	t<10s	$T_A = 25^{\circ}C$ $T_A = 70^{\circ}C$	ID	8.4 6.6	А
Maximum Continuous Body Diode Forward Current (Note 5)			ls	2	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I <sub>DM</sub>	42	A
Avalanche Current (Notes 6 & 7) L = 0.1mH			I <sub>AR</sub>	17	А
Repetitive Avalanche Energy (Notes 6 & 7) L = 0.1mH			E <sub>AR</sub>	14	mJ

## **Thermal Characteristics**

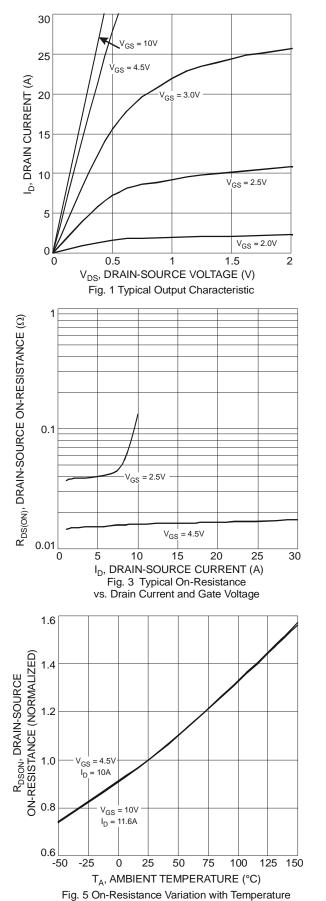
Characteristic		Symbol	Value	Units	
Total Power Dissipation (Note 4)		PD	1.17	W	
Thermal Resistance, Junction to Ambient (Note 4)	Steady State	Р	107	°C/W	
mermai Resistance, Junction to Amblent (Note 4)	t<10s	$R_{ heta JA}$	61		
Total Power Dissipation (Note 5)		PD	1.5	W	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Р	83	°C/W	
mermai Resistance, Junction to Ambient (Note 5)	t<10s	$R_{ heta JA}$	49		
Thermal Resistance, Junction to Case		$R_{ ext{ heta}JC}$	14.5		
Operating and Storage Temperature Range		TJ, TSTG	-55 to 150	°C	

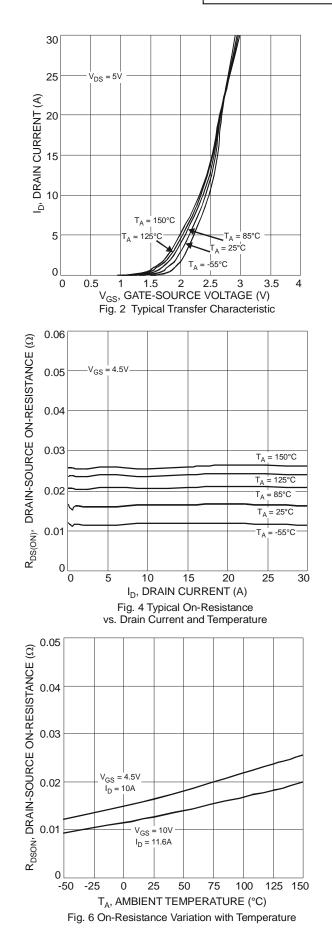
## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)			- 76				
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current TJ = 25°C	I <sub>DSS</sub>	-	-	1.0	μA	$V_{DS} = 30V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	-	-	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.8	-	1.6	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-Resistance	Provide	-	12	16	mΩ	$V_{GS} = 10V, I_D = 9A$	
	R <sub>DS(on)</sub>		16	22		$V_{GS} = 4.5V, I_D = 7A$	
Forward Transfer Admittance	Y <sub>fs</sub>	-	8	-	S	$V_{DS} = 10V, I_D = 9A$	
Diode Forward Voltage	V <sub>SD</sub>	-	0.72	0.94	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	-	798	-	pF	$-V_{DS} = 10V, V_{GS} = 0V,$ -f = 1.0MHz	
Output Capacitance	C <sub>oss</sub>	-	128	-	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	122	-	pF		
Gate Resistance	R <sub>g</sub>	ľ	1.37	-	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge	Qg	-	8.56	-	nC	$V_{GS} = 5V, V_{DS} = 15V,$ $I_D = 9A$	
Gate-Source Charge	Q <sub>gs</sub>	ľ	1.8	-	nC		
Gate-Drain Charge	Q <sub>gd</sub>	-	2.5	-	nC		
Turn-On Delay Time	t <sub>D(on)</sub>	-	5.03	-	ns		
Turn-On Rise Time	tr	-	4.50	-	ns	$V_{DD} = 15V, V_{GEN} = 10V,$	
Turn-Off Delay Time	t <sub>D(off)</sub>	-	26.33	-	ns	$R_L = 15\Omega, R_G = 6\Omega, I_D = 1A$	
Turn-Off Fall Time	t <sub>f</sub>	-	8.55	-	ns	<u>]</u>	

4. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. 6.  $I_{AR}$  and  $E_{AR}$  rating are based on low frequency and duty cycles to keep  $T_{J} = 25^{\circ}$ C 7. Applicable to products manufactured with Data Code "1146" (Nov, 2011) and newer. 8. Short duration pulse test used to minimize self-heating effect. 9. Guaranteed by design. Not subject to product testing. Notes:









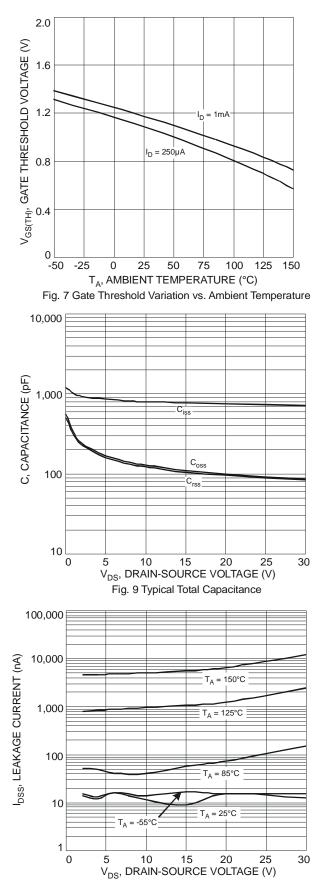
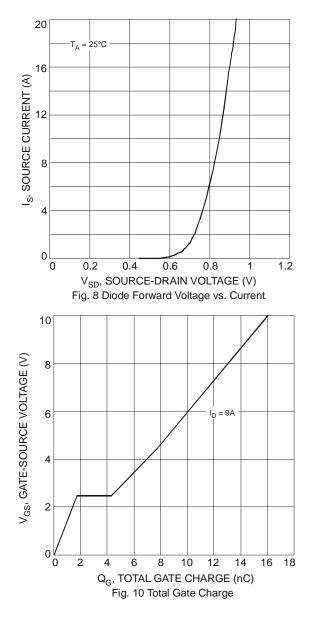
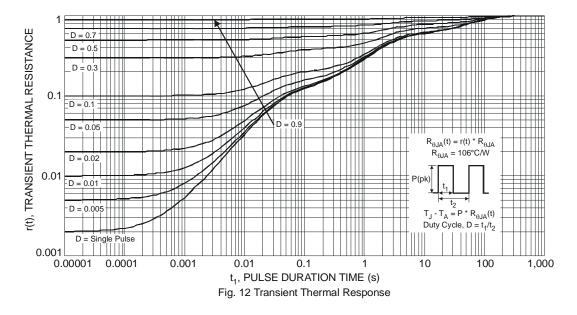


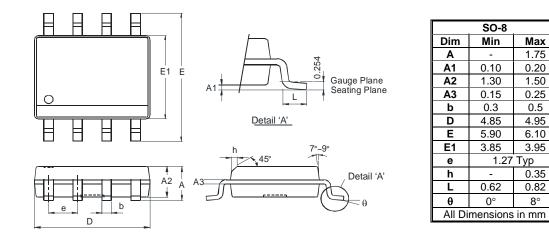
Fig. 11 Typical Leakage Current vs. Drain-Source Voltage



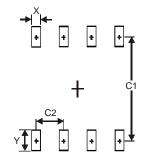




# **Package Outline Dimensions**



# **Suggested Pad Layout**



Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27



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